

CLAIMS

What is claimed is:

1. An integrated circuit structure comprising:
a substrate;
a plurality of different height devices positioned on said substrate;
a passivating layer positioned above said substrate and between said devices;
a wiring layer above said passivating layer,
wherein the tallest devices are in direct contact with said wiring layer and shorter devices are connected to said wiring layer by contacts extending through said passivating layer.
2. The integrated circuit in claim 1, further comprising a via layer above said wiring layer, wherein said tallest devices include second contacts directly connected to said via layer.
3. The integrated circuit in claim 2, wherein said second contacts extend through said wiring layer to said via layer.
4. The integrated circuit in claim 2, wherein said second contacts are positioned within said wiring layer.
5. The integrated circuit in claim 4, wherein said second contacts within said wiring layer comprise a different material than said wiring within said wiring layer.
6. The integrated circuit in claim 1, wherein said tallest devices comprise a different type of device than said shorter devices.